Adhesives and Tapes

Electrically Conductive Product and Properties Guide Electrical and Industrial Applications

Duralco 12X Series

Electrically Conductive Adhesives

Duralco® Conductive adhesives and potting compounds provide the conductivity required for many high temperature electronic and industrial applications. They will bond to glass, ceramics, metals and plastics, offering excellent resistance to most chemicals and solvents. Applications include solder replacement, semi-conductor bonding, shielding, electronics, circuit board repair, etc.

Duralco 120 - 260°C Silver based

Epoxy that cures at room temperature to form electrically conductive bond lines for use up to 260°C. Ideal for forming electrically conductive bonds, attaching heat sensitive components and as a solder replacement.

Duralco 122 - 260°C Nickel based

This Nickel filled adhesive and casting epoxy is specially formulated to provide an economical alternative to silver filled electrically conductive epoxies. Ideal for use in applications where the ultimate in electrical conductivity is not required.

Duralco 124 - 340°C Ultra Temp, Silver based

A two component, silver filled adhesive for High Power applications. Just mix and cure with mild heat.

Duralco 125 - 230°C Flexible, Silver based

Easy to use, "one to one", applicator kit. Just dispense, mix and apply this smooth creamy paste and cure at room temperature. Bonds to most metals, ceramics and plastics to form stress free, electrically conductive bonds.

Duralco 126 - 230°C One component, Silver filled A single component highly conductive epoxy specifically designed for production applications. No mixing, no mess, just dispense and heat cure. Commonly used in automatic dispensing equipment.

Duralco 127 - 200°C Graphite based

Easy to use, "one to one", applicator kit. Just dispense, mix and apply. This smooth creamy paste cures at room temperature and is ideal for low cost production applications. Can be used in automatic dispensing equipment.





Performance Chart

Part Number	Volume Resistance	Thermal Conductivity	Cure Cycle Hours @	Cure Cycle Minutes @	Size
	Ω-cm	W/mºC	25°C	95°C	oz
120	0.0*	7.20	16-24	10	2
122	0.7	2.16	16-24	10	4
124	0.002	7.20	4@120°C	N/A	2
125	0.002	5.76	16-24	20	1
126	0.002	7.20	1/2@135°C	10@160°C	2
127	0.02	3.60	16-24	20	2.5
* Develope a church					

* Denotes 0.00008 actual

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